



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

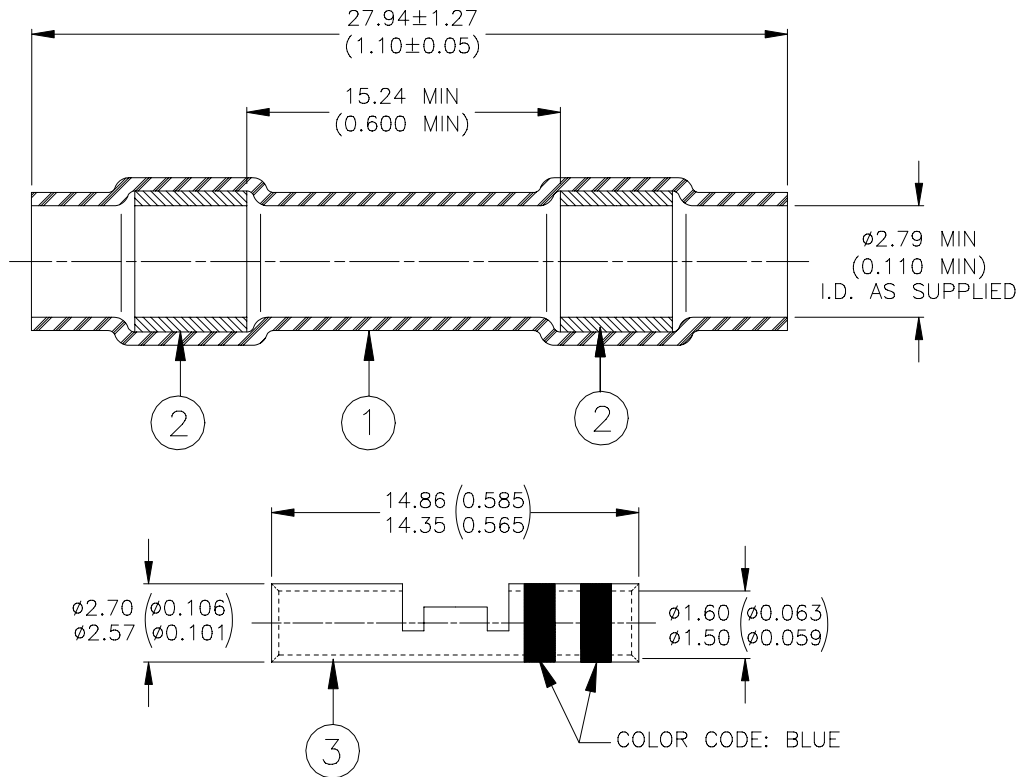
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## SPECIFICATION CONTROL DRAWING



### MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent blue, radiation cross-linked modified polyvinylidene fluoride.
2. MELTABLE INSERTS: Immersion resistant thermoplastic.
3. CRIMP SPLICER: Base Metal: Copper Alloy 101 or 102 per ASTM B-75.  
Plating: Tin, per MIL-T-10727, Type 1.

### INSTALLATION DATA:

Conductor size range of Crimp Splicer: Minimum – 22, Maximum – 18  
 Insulation Diameters in which part will seal: Minimum – 0.64 (0.025), Maximum – 2.79 (0.110)

### APPLICATION

1. These parts are designed to provide immersion resistant in-line splices of 1 to 1, 1 to 2 or 2 to 2 with wires falling within size range listed above, and having insulations rated for at least 125°C.
2. Crimp splicer may be installed with Raychem AD-1377 Crimp Tool using the blue nest marked 16-20.
3. Parts will meet requirements of U.S. Military Specification MIL-S-81824/1.
4. Acceptance sampling shall be accordance with Paragraph 4.6.1 of MIL-S-81824.
5. Packing and packaging shall be accordance with Section 5, Level C, of MIL-S-81824.
6. This document takes precedence over documents referenced herein.
7. For assembly procedure, see Raychem Process Standard RCPS 200-20.

<b>Raychem Interconnect</b> <small>a division of tyco Electronics</small> 300 Constitution Drive Menlo Park, CA 94025, USA		THERMOFIT DEVICES	TITLE : <b>IN-LINE SPLICE SEALING SYSTEM</b>				
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS. INCHES DIMENSIONS ARE BETWEEN BRACKETS.			DOCUMENT NO.: <b>D-436-0147</b>				
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A  ROUGHNESS IN MICRON	Raychem reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.	DCR NUMBER: <b>D001282</b>		REPLACES: <b>N/A</b>		
DRAWN BY: M. FORONDA	DATE: 14-Nov.-00	PROD. REV. A	DOC ISSUE: 1	SCALE: None	SIZE: A	SHEET: 1 of 1	

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